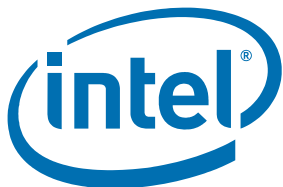


Technical Specifications

Chassis Configuration	<ul style="list-style-type: none"> • 6U rack mount or pedestal based 	Server Compute Module	<p>Processors</p> <ul style="list-style-type: none"> • Based on the Intel® 5000P series chipset and supports multi-core Intel® Xeon® processors <p>Intel® 5000P chipset family, including:</p> <ul style="list-style-type: none"> • Intel® 5000P Memory Controller Hub • Intel® 6321ESB I/O Controller Hub <p>Memory</p> <ul style="list-style-type: none"> • 8 fully-buffered DIMM (FBDIMM) slots supporting up to 32GB of memory <p>On-board host bus adapter</p> <ul style="list-style-type: none"> • LSI* 1064e SAS controller <p>LAN</p> <ul style="list-style-type: none"> • Two integrated 10/100/1000 Ethernet ports and two optional 10/100/1000 Ethernet ports via the Mezzanine Card <p>On-board Video</p> <ul style="list-style-type: none"> • Server Compute Module ATI* ES1000 video controller with 16 MB of DDR SDRAM <p>External Connectors</p> <ul style="list-style-type: none"> • Two USB 2.0 ports • Video connector <p>Internal Connectors</p> <ul style="list-style-type: none"> • One Intel® I/O Mezzanine Connector supporting an optional Mezzanine Card
Front	<ul style="list-style-type: none"> • Storage drive bay supports 14 hot-swap 2.5" SAS drives • Up to 6 Server Compute Modules • One Hot Swap I/O Fan Module 	Mezzanine Card	<ul style="list-style-type: none"> • Provides additional dual-channel Ethernet ports • Intel® Modular Server Accessory AXXGBIOMEZ
Rear	<ul style="list-style-type: none"> • One Management Module • Up to two Ethernet Switch Modules • Up to two Storage Control Modules • Four power supply bays for 3+1 redundancy • Two hot swap fan modules 	Chassis Size	<ul style="list-style-type: none"> • Height: 10.3 inches (6U) • Width: 17.5 inches • Depth: 28.4 inches • Weight with full configuration: 187 lbs.
Mid-Plane	<ul style="list-style-type: none"> • Connects subsystems to the Management Module • Designed for multiple generations of Server Compute Modules • Provides I/O for the system 	Chassis Power Requirements	<ul style="list-style-type: none"> • Up to four 1,000-watt DC output power supply modules with 110-240V AC input • Full system configuration power requirements: 3,000 watts
Storage Control Module	<ul style="list-style-type: none"> • RAID: 0, 1, 1E, 5, 6, 10 • I/O: <ul style="list-style-type: none"> • External extended storage mini SAS port • Six internal 3Gbps SAS channels • Active-Active redundancy • Battery Backup 	Chassis Acoustical Noise Emissions	<ul style="list-style-type: none"> • Sound power 70 dB maximum
Ethernet Switch Module	<p>Ports</p> <ul style="list-style-type: none"> • Ten external 10/100/1000 GbE full-duplex ports • Twelve internal 1-GbE full-duplex ports <p>Management</p> <ul style="list-style-type: none"> • Port, VLAN, and Advanced Switch Configuration via the Management Module <p>Layer 2+ features</p> <ul style="list-style-type: none"> • ACL, QOS, Link Aggregation, 10K Jumbo Frame support, VLAN support, STP, and RSTP • Non-blocking I/O, wire-speed performance 	Chassis Environment	<ul style="list-style-type: none"> • Temperature operating: 10°C to 35°C 50°F to 95°F • Temperature non-operating: -40°C to 70°C -40°F to 158°F • Altitude: -30 to 1,500 m -100 to 5,000 ft
Management Module	<p>I/O</p> <ul style="list-style-type: none"> • External 10/100 Ethernet port • External serial port <p>Remote Management</p> <ul style="list-style-type: none"> • Remote Media • Remote Console 	Chassis Safety	<ul style="list-style-type: none"> • UL60 950, CSA60 950, AS/NZS 3562, GB4943-1995, EN60 950 and 73/23/EEC, IEC 60 950, EMKO-TSE (74-SEC) 207/94, GOST-R 50377-92
		Chassis Emissions	<ul style="list-style-type: none"> • Certified to FCC Class A; tested to CISPR 22 Class A, EN 55022 Class A and 89/336/EEC, VCCI Class A, AS/NZS 3548 Class A, ICES-003 Class A, GB9254-1998, MIC Notice 1997-42 Class A, GOST-R 29216-91 Class A, BSMI CNS13438



Ultra Digital

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL® AND ULTRA DIGITAL PRODUCTS. EXCEPT AS PROVIDED IN INTEL'S, AND ULTRA DIGITAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL AND ULTRA DIGITAL ASSUMES NO LIABILITY WHATSOEVER, INTEL AND ULTRA DIGITAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO SALE AND/OR USE OF INTEL AND ULTRA DIGITAL PRODUCTS, INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT, OR OTHER INTELLECTUAL PROPERTY RIGHT.

Intel, Intel logo, and Intel Xeon are trademarks of Intel Corporation in the U.S. and other countries.*other names and brands may be claimed as the property of others. Ultra Digital, Ultra Digital Logo are trademarks of Ultra Digital Corporation in the U.S. and other countries.

Copyright ©2007 Intel Corporation and Copyright ©2009 Ultra Digital Corporation all rights reserved.